IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Art Unit: 2827

fe Application: Yeo, et al. Serial No.: 10/078,718

Filed: February 19, 2002

For: Enhanced Chip Scale Package For Wire Bond Dies

Mail Stop DD Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. 1.56, counsel wishes to make of record the attached items of information for the Examiner's consideration in connection with this application. Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application mailed 30 June 2003, which is less than 3 months from this filing. Also enclosed is a form PTO-1449 for the Examiner's convenience in making such consideration of record. Inclusion herein of any particular item of information is not to be construed as an admission that same is prior art.

The Commissioner is hereby authorized to charge any fees that may be required or credit any overpayment to Deposit Account 18-1167.

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Respectfully submitted,

Michael D. Murphy Registration No. 44,958

Date: August 6, 2003

File No.: 4795-002

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION PURSUANT TO 37 CFR §1.97 & 1.98					I Docket Number: I Serial Nur I 4795-002 I 10/078,71				
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation not in conformance and not considered. Include copy of this form with next communication to the applicant.